



# Wireless Components

ASK/FSK Single Conversion Receiver TDA 5210 Version 3.0

Specification May 2001

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Page (in previous Version)	Page(s) (in current Version)	Subjects (major changes since last revision)	
Product Info, 2-2	Product Info, 2-2	typ. supply current changed	
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4-4	4-4	value of a changed to 1.414	
4-8	4-8	FSK demodulator gain changed to 140μV/kHz	
4-13	4-13	value for C2 changed to 22nF according to bill of materials, $\tau_2$ and $T_2$ changed	
5-3	5-3	min. supply current limits added, max. limits changed	
5-4	5-4	supply current max. limit changed, min. limit added	
5-5	5-5	NF <sub>LNA</sub> specification removed	
5-6	5-6	3VOUT min. & max. limits changed, TAGC typ. & max. values changed, IFO: NF <sub>mix</sub> and RF/IF isolation removed	
5-7	5-7	Section "SLICER" reworked, max. datarate at given load capacitance quoted, high output voltage limits changed, precharge current: min., max. limits changed, PDO load and leakage currents limits and typ. values changed,	
5-8	5-8	FSK demodulation gain min. limit changed	
5-9	5-9	PDWN-current max. limit changed, supply currents min. limits added, max. limits changed, 3VOUT min. & max. limits changed, I <sub>TAGC_out</sub> limits changed	
5-10	5-10	Section "SLICER" reworked, max. datarate at given load capacitance quoted, high output voltage limits changed, precharge current: min., max. limits changed, PDO output voltage removed	
5-15	5-15	C18 value changed	

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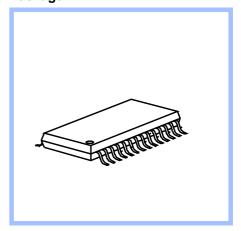
**Product Info** 

# **Product Info**

#### **General Description**

The IC is a very low power consumption single chip FSK/ASK Superheterodyne Receiver (SHR) for the frequency bands 810 to 870 MHz and 400 to 440 MHz that is pin compatible with the ASK Receiver TDA5200. The IC offers a high level of integration and needs only a few external components. The device contains a low noise amplifier (LNA), a double balanced mixer, a fully integrated VCO, a PLL synthesiser, a crystal oscillator, a limiter with RSSI generator, a PLL FSK demodulator, a data filter, a data comparator (slicer) and a peak detector. Additionally there is a power down feature to save battery life.

#### **Package**



#### **Features**

- Low supply current (typ. at 868MHz I<sub>s</sub> = 5.9mA in FSK mode, I<sub>s</sub> = 5.2mA in ASK mode)
- Supply voltage range 5V ±10%
- Power down mode with very low supply current (50nA typ)
- FSK and ASK demodulation capability
- Fully integrated VCO and PLL Synthesiser
- ASK sensitivity < -107dBm</p>

- Selectable frequency ranges 810-870 MHz and 400-440 MHz
- Limiter with RSSI generation, operating at 10.7MHz
- Selectable reference frequency
- 2nd order low pass data filter with external capacitors
- Data slicer with self-adjusting threshold
- FSK sensitivity <-100dBm

#### **Application**

- Keyless Entry Systems
- Remote Control Systems
- Alarm Systems
- Low Bitrate Communication Systems

#### **Ordering Information**

Туре	Ordering Code	Package
TDA 5210	Q67037-A1100	P-TSSOP-28-1
samples available on tape and reel		

# Table of Contents

1	Table	of Contents	İ
2	Produ	ct Description	1
	2.1	Overview	2
	2.2	Application	2
	2.3	Features	2
	2.4	Package Outlines	3
3	Funct	ional Description	1
•	3.1	Pin Configuration	2
	3.2	Pin Definition and Function.	3
	3.3	Functional Block Diagram	9
	3.4	Functional Blocks	9
	3.4.1	Low Noise Amplifier (LNA)	9
	3.4.2	Mixer	10
	3.4.3	PLL Synthesizer	10
	3.4.4	Crystal Oscillator	11
	3.4.5	Limiter	11
	3.4.6	FSK Demodulator	11
	3.4.7	Data Filter	12
	3.4.8	Data Slicer	12
	3.4.9	Peak Detector	12
	3 4 10	Bandgap Reference Circuitry	13

4	Appli	cations	1
	4.1	Choice of LNA Threshold Voltage and Time Constant	2
	4.2	Data Filter Design	4
	4.3	Quartz Load Capacitance Calculation	5
	4.4	Quartz Frequency Calculation	6
	4.5	Data Slicer Threshold Generation	7
	4.6	ASK/FSK Switch Functional Description	8
	4.6.1	FSK Mode	8
	4.6.2	ASK Mode	10
	4.7	Principle of the Precharge Circuit	11
5	Refer	ence	1
	5.1	Electrical Data	2
	5.1.2	Operating Range	3
	5.1.3	AC/DC Characteristics at TAMB = 25°C	4
	5.1.4	AC/DC Characteristics at TAMB = -40 to 105°C	9
	5.2	Test Circuit	12
	5.3	Test Board Layouts	13
	5.4	Bill of Materials	15

# Product Description

Con	ntents of this Chapter	
2.1	Overview	2-2
2.2	Application	2-2
2.3	Features	2-2
2 4	Deales as Cuttings	2.2



**Product Description** 

#### 2.1 Overview

The IC is a very low power consumption single chip FSK/ASK Superheterodyne Receiver (SHR) for the frequency bands 810 to 870 MHz and 400 to 440 MHz that is pin compatible with the ASK Receiver TDA5200. The IC offers a high level of integration and needs only a few external components. The device contains a low noise amplifier (LNA), a double balanced mixer, a fully integrated VCO, a PLL synthesiser, a crystal oscillator, a limiter with RSSI generator, a PLL FSK demodulator, a data filter, a data comparator (slicer) and a peak detector. Additionally there is a power down feature to save battery life.

# 2.2 Application

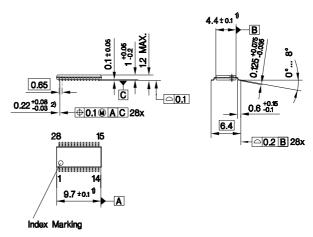
- Keyless Entry Systems
- Remote Control Systems
- Alarm Systems
- Low Bitrate Communication Systems

#### 2.3 Features

- Low supply current (at 868MHz I<sub>s</sub> = 5.9 mA typ. FSK mode, 5.2mA typ. ASK mode)
- Supply voltage range 5V ±10%
- Power down mode with very low supply current (50nA typ)
- FSK and ASK demodulation capability
- Fully integrated VCO and PLL Synthesiser
- RF input sensitivity ASK < -107dBm</p>
- RF input sensitivity FSK < -100dBm
- Selectable frequency ranges 810-870 MHz and 400-440 MHz
- Selectable reference frequency
- Limiter with RSSI generation, operating at 10.7MHz
- 2nd order low pass data filter with external capacitors
- Data slicer with self-adjusting threshold

#### **Product Description**

# 2.4 Package Outlines



- 1) Does not include plastic or metal protrusion of 0.15 max. per side
- 2) Does not include dambar protrusion

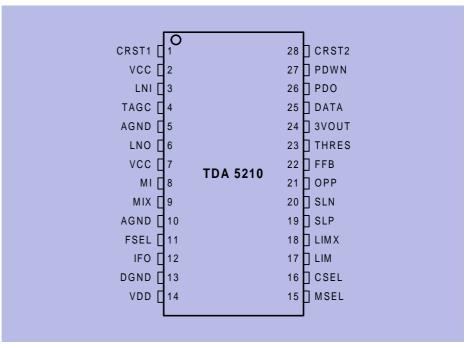
P\_TSSOP\_28.EPS

Figure 2-1 P-TSSOP-28-1 package outlines

Con	tents of this Chapter	
3.1	Pin Configuration	3-2
3.2	Pin Definition and Function	3-3
3.3	Functional Block Diagram	3-9
3.4	Functional Blocks	3-9



# 3.1 Pin Configuration



Pin\_Configuration\_5210.wmf

Figure 3-1 IC Pin Configuration

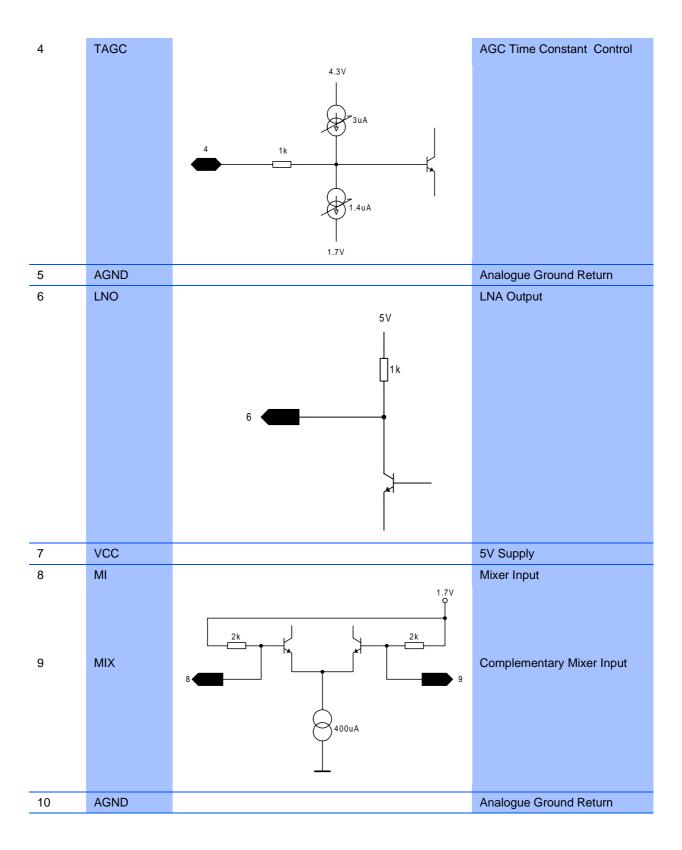
# 3.2 Pin Definition and Function

In the subsequent table the internal circuits connected to the pins of the device are shown. ESD-protection circuits are omitted to ease reading.

.

Table 3-	Pin Definition	and Function	
Pin No.	Symbol	Equivalent I/O-Schematic	Function
1	CRST1	4.15V 50uA	External Crystal Connector 1
2	VCC		5V Supply
3	LNI	57uA 3 500uA	LNA Input







11	FSEL		868/434 MHz Operating Frequency Selector
		1.2V • 750	
		2k	
		11	
12	IFO		10.7 MHz IF Mixer Output
		1	
		300uA	
		0.01/	
		2.2V	
		60	
		12	
		↓ ☐ 4.5k	
		\ \	
		$\perp$	
13	DGND		Digital Ground Return
14	VDD		5V Supply (PLL Counter Cir-
			cuitry)
15	MSEL	I	ASK/FSK Modulation Format Selector
		○ 1.2V	
		3.6k	
		15	



16	CSEL	• 1.2V	6.xx or 13.xx MHz Quartz Selector
		16 80k	
17	LIM	2.4V 15k	Limiter Input
18	LIMX	17 330 75uA	Complementary Limiter Input
19	SLP	19 3k 15uA 80µA	Data Slicer Positive Input



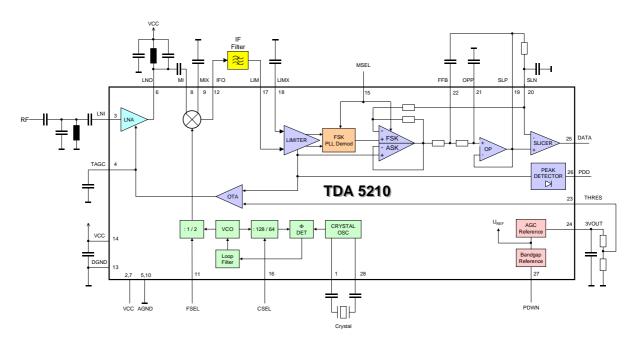
20	SLN	5uA	Data Slicer Negative Input
		20 10k	
21	OPP	5uA	OpAmp Noninverting Input
		21	
22	FFB	5uA	Data Filter Feedback Pin
		22 100k	
23	THRES	5uA	AGC Threshold Input
		23 10k	
24	3VOUT	24 20k	3V Reference Output
		3.1٧	



25	DATA	25 ————————————————————————————————————	Data Output
26	PDO	26	Peak Detector Output
27	PDWN	220k	Power Down Input
28	CRST2	4.15V 50uA	External Crystal Connector 2



### 3.3 Functional Block Diagram



Function\_5200.wmf

Figure 3-2 Main Block Diagram

#### 3.4 Functional Blocks

### 3.4.1 Low Noise Amplifier (LNA)

The LNA is an on-chip cascode amplifier with a voltage gain of 15 to 20dB. The gain figure is determined by the external matching networks situated ahead of LNA and between the LNA output **LNO** (Pin 6) and the Mixer Inputs **MI** and **MIX** (Pins 8 and 9). The noise figure of the LNA is approximately 3dB, the current consumption is 500µA. The gain can be reduced by approximately 18dB. The switching point of this AGC action can be determined externally by applying a threshold voltage at the **THRES** pin (Pin 23). This voltage is compared internally with the received signal (RSSI) level generated by the limiter circuitry. In case that the RSSI level is higher than the threshold voltage the LNA gain is reduced and vice versa. The threshold voltage can be generated by attaching a voltage divider between the **3VOUT** pin (Pin 24) which provides a temperature stable 3V output generated from the internal bandgap voltage and the **THRES** pin as described in Section 4.1. The time constant of the AGC action can be deter-



mined by connecting a capacitor to the **TAGC** pin (Pin 4) and should be chosen along with the appropriate threshold voltage according to the intended operating case and interference scenario to be expected during operation. The optimum choice of AGC time constant and the threshold voltage is described in Section 4.1.

#### 3.4.2 Mixer

The Double Balanced Mixer downconverts the input frequency (RF) in the range of 400-440MHz/810-870MHz to the intermediate frequency (IF) at 10.7MHz with a voltage gain of approximately 21dB by utilising either high- or low-side injection of the local oscillator signal. In case the mixer is interfaced only single-ended, the unused mixer input has to be tied to ground via a capacitor. The mixer is followed by a low pass filter with a corner frequency of 20MHz in order to suppress RF signals to appear at the IF output (IFO pin). The IF output is internally consisting of an emitter follower that has a source impedance of approximately 330  $\Omega$  to facilitate interfacing the pin directly to a standard 10.7MHz ceramic filter without additional matching circuitry.

#### 3.4.3 PLL Synthesizer

The Phase Locked Loop synthesiser consists of a VCO, an asynchronous divider chain, a phase detector with charge pump and a loop filter and is fully implemented on-chip. The VCO is including on-chip spiral inductors and varactor diodes. It's nominal centre frequency is 840MHz, the operating range guaranteed over the temperature range specified is 820 to 860MHz. Depending on whether high- or low-side injection of the local oscillator is used the receive frequency ranges are 810 to 840 and 840 to 870MHz or 400 to 420 and 420 to 440MHz (see also Section 4.4). No additional external components are necessary.

The oscillator signal is fed both to the synthesiser divider chain and to the down-converting mixer. In case of operation in the 400 to 440 MHz range, the signal is divided by two before it is fed to the mixer. This is controlled by the selection pin **FSEL** (Pin 11) as described in the following table. The overall division ratio of the divider chain can be selected to be either 128 or 64, depending on the frequency of the reference oscillator quartz (see below and Section 4.4). The loop filter is also realised fully on-chip.

Table 3-2 FSEL Pin Operating States		
FSEL	RF Frequency	
Open	400-440 MHz	
Shorted to ground	810-870 MHz	



#### 3.4.4 Crystal Oscillator

The on-chip crystal oscillator circuitry allows for utilisation of quartzes both in the 6 and 13MHz range as the overall division ratio of the PLL can be switched between 64 and 128 via the **CSEL** (Pin 16) pin according to the following table.

Table 3-3 CSEL Pin Operating States				
CSEL	Crystal Frequency			
Open	6.xx MHz			
Shorted to ground	13.xx MHz			

The calculation of the value of the necessary quartz load capacitance is shown in Section 4.3, the quartz frequency calculation is explained in Section 4.4.

#### 3.4.5 Limiter

The Limiter is an AC coupled multistage amplifier with a cumulative gain of approximately 80 dB that has a bandpass-characteristic centred around 10.7 MHz. It has a typical input impedance of 330  $\Omega$  to allow for easy interfacing to a 10.7 MHz ceramic IF filter. The limiter circuit also acts as a Receive Signal Strength Indicator (RSSI) generator which produces a DC voltage that is directly proportional to the input signal level as can be seen in Figure 4-2. This signal is used to demodulate ASK-modulated receive signals in the subsequent baseband circuitry. The RSSI output is applied to the modulation format switch, to the Peak Detector input and to the AGC circuitry.

In order to demodulate ASK signals the MSEL pin has to be left open as described in the next chapter.

#### 3.4.6 FSK Demodulator

To demodulate frequency shift keyed (FSK) signals a PLL circuit is used that is contained fully on chip. The Limiter output differential signal is fed to the linear phase detector as is the output of the 10.7 MHz center frequency VCO. The demodulator gain is typically  $140\mu V/kHz$ . The passive loop filter output that is comprised fully on chip is fed to both the VCO and the modulation format switch described in more detail below. This signal is representing the demodulated signal with high frequencies applied to the demodulator demodulated to logic ones and low frequencies demodulated to logic zeroes. Please note that due to this behaviour a sign inversion of the data occurs in case of high-side injection of the local oscillator at receive frequencies below 840 or 420MHz, respectively. See also .

The modulation format switch is actually a switchable amplifier with an AC gain of 11 that is controlled by the **MSEL** pin (Pin 15) as shown in the following table. This gain was chosen to facilitate detection in the subsequent circuits. The DC

gain is 1 in order not to saturate the subsequent Data Filter wih the DC offset produced by the demodulator in case of large frequency offsets of the IF signal. The resulting frequency characteristic and details on the principle of operation of the switch are described in Section 4.6.

Table 3-4 MSEL Pin Operating States				
MSEL	Modulation Format			
Open	ASK			
Shorted to ground	FSK			

The demodulator circuit is switched off in case of reception of ASK signals.

#### 3.4.7 Data Filter

The data filter comprises an OP-Amp with a bandwidth of 100kHz used as a voltage follower and two  $100k\Omega$  on-chip resistors. Along with two external capacitors a 2nd order Sallen-Key low pass filter is formed. The selection of the capacitor values is described in Section 4.2.

#### 3.4.8 Data Slicer

The data slicer is a fast comparator with a bandwidth of 100 kHz. This allows for a maximum receive data rate of up to 100kBaud. The maximum achievable data rate also depends on the IF Filter bandwidth and the local oscillator tolerance values. Both inputs are accessible. The output delivers a digital data signal (CMOS-like levels) for sbsequent circuits. The self-adjusting threshold on pin 20 its generated by RC-term or peak detector depending on the baseband coding scheme. The data slicer threshold generation alternatives are described in more detail in Section 4.5.

#### 3.4.9 Peak Detector

The peak detector generates a DC voltage which is proportional to the peak value of the receive data signal. An external RC network is necessary. The input is connected to the output of the RSSI-output of the Limiter, the output is connected to the **PDO** pin (Pin 26 ). This output can be used as an indicator for the received signal strength to use in wake-up circuits and as a reference for the data slicer in ASK mode. The maximum output current is typically 950 $\mu$ A, the discharge current is lower than 2 $\mu$ A. Note that the RSSI level is also output in case of FSK mode.



# 3.4.10 Bandgap Reference Circuitry

A Bandgap Reference Circuit provides a temperature stable reference voltage for the device. A power down mode is available to switch off all subcircuits which is controlled by the PWDN pin (Pin 27) as shown in the following table. The supply current drawn in this case is typically 50nA.

Table 3-5 PDWN Pin Operating States				
PDWN	Operating State			
Open or tied to ground	Powerdown Mode			
Tied to Vs	Receiver On			

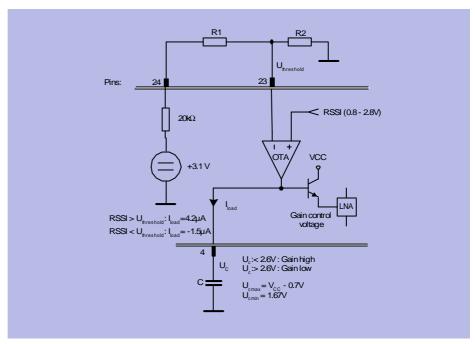
#### **Contents of this Chapter**

4.1	Choice of LNA Threshold Voltage and Time Constant	. 4-2
4.2	Data Filter Design	. 4-4
4.3	Quartz Load Capacitance Calculation	. 4-5
4.4	Quartz Frequency Calculation	. 4-6
4.5	Data Slicer Threshold Generation	. 4-7
4.6	ASK/FSK Switch Functional Description	. 4-8
4.7	Principle of the Precharge Circuit	4-11



### 4.1 Choice of LNA Threshold Voltage and Time Constant

In the following figure the internal circuitry of the LNA automatic gain control is shown.



LNA\_autom.wmf

Figure 4-1 LNA Automatic Gain Control Circuitry

The LNA automatic gain control circuitry consists of an operational transimpedance amplifier that is used to compare the received signal strength signal (RSSI) generated by the Limiter with an externally provided threshold voltage  $U_{thres}$ . As shown in the following figure the threshold voltage can have any value between approximately 0.8 and 2.8V to provide a switching point within the receive signal dynamic range.

This voltage  $U_{thres}$  is applied to the **THRES** pin (Pin 23) The threshold voltage can be generated by attaching a voltage divider between the **3VOUT** pin (Pin 24) which provides a temperature stable 3V output generated from the internal bandgap voltage and the **THRES** pin. If the RSSI level generated by the Limiter is higher than  $U_{thres}$ , the OTA generates a positive current  $I_{load}$ . This yields a voltage rise on the **TAGC** pin (Pin 4). Otherwise, the OTA generates a negative current. These currents do not have the same values in order to achieve a fast-attack and slow-release action of the AGC and are used to charge an external capacitor which finally generates the LNA gain control voltage.



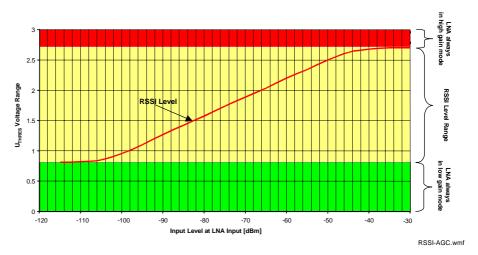


Figure 4-2 RSSI Level and Permissive AGC Threshold Levels

The switching point should be chosen according to the intended operating scenario. The determination of the optimum point is described in the accompanying Application Note, a threshold voltage level of 1.8V is apparently a viable choice. It should be noted that the output of the **3VOUT** pin is capable of driving up to  $50\mu\text{A}$ , but that the **THRES** pin input current is only in the region of 40nA. As the current drawn out of the **3VOUT** pin is directly related to the receiver power consumption, the power divider resistors should have high impedance values. The sum of R1 and R2 has to be  $600k\Omega$  in order to yield 3V at the **3VOUT** pin. R1 can thus be chosen as  $240k\Omega$ , R2 as  $360k\Omega$  to yield an overall **3VOUT** output current of  $5\mu\text{A}^1$  and a threshold voltage of 1.8V

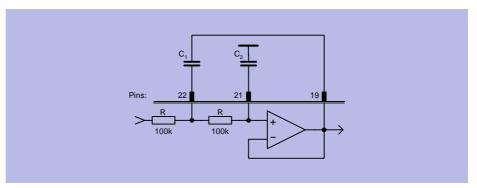
**Note:** If the LNA gain shall be kept in either high or low gain mode this has to be accomplished by tying the **THRES** pin to a fixed voltage. In order to achieve high gain mode operation, a voltage higher than 2.8V shall be applied to the **THRES** pin, such as a short to the **3VOLT** pin. In order to achieve low gain mode operation a voltage lower than 0.7V shall be applied to the **THRES**, such as a short to ground.

As stated above the capacitor connected to the **TAGC** pin is generating the gain control voltage of the LNA due to the charging and discharging currents of the OTA and thus is also responsible for the AGC time constant. As the charging and discharging currents are not equal two different time constants will result. The time constant corresponding to the charging process of the capacitor shall be chosen according to the data rate. According to measurements performed at Infineon the capacitor value should be greater than 47nF.

1. note the  $20k\Omega$  resistor in series with the 3.1V internal voltage source

## 4.2 Data Filter Design

Utilising the on-board voltage follower and the two  $100k\Omega$  on-chip resistors a 2nd order Sallen-Key low pass data filter can be constructed by adding 2 external capacitors between pins 19 (SLP) and 22 (FFB) and to pin 21 (OPP) as depicted in the following figure and described in the following formulas<sup>1</sup>.



Filter Design.wmf

Figure 4-3 Data Filter Design

(1)(2)

$$C1 = \frac{2Q\sqrt{b}}{R2\Pi f_{3dB}} \qquad C2 = \frac{\sqrt{b}}{4QR\Pi f_{3dB}}$$

with

$$Q = \frac{\sqrt{b}}{a}$$
 (3)the quality factor of the poles

where

in case of a Bessel filter a = 1.3617, b = 0.618 and thus Q = 0.577

and in case of a Butterworth filter a = 1.414, b = 1 and thus Q = 0.71

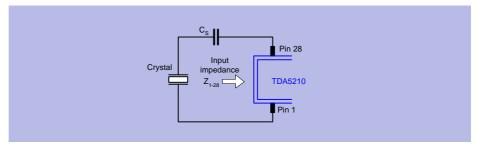
Example: Butterworth filter with  $f_{3dB} = 5kHz$  and  $R = 100k\Omega$ :

$$C_1 = 450pF, C_2 = 225pF$$

1. taken from Tietze/Schenk: Halbleiterschaltungstechnik, Springer Berlin, 1999

## 4.3 Quartz Load Capacitance Calculation

The value of the capacitor necessary to achieve that the quartz oscillator is operating at the intended frequency is determined by the reactive part of the negative resistance of the oscillator circuit as shown in Section 5.1.3 and by the quartz specifications given by the quartz manufacturer.



Quartz load wmi

Figure 4-4 Determination of Series Capacitance Value for the Quartz Oscillator

Crystal specified with load capacitance

$$C_s = \frac{1}{\frac{1}{C_l} + 2\pi f X_L}$$

with C<sub>I</sub> the load capacitance (refer to the quartz crystal specification).

#### Examples:

6.7 MHz: 
$$C_L = 12 \text{ pFX}_L = 695\Omega C_S = 8.9 \text{ pF}$$
  
13.4 MHz:  $C_L = 12 \text{ pFX}_L = 1010 \Omega C_S = 5.9 \text{ pF}$ 

These values may be obtained in high accuracy by putting two capacitors in series to the quartz, such as 22pF and 15pF in the 6.7MHz case and 22pF and 8.2pF in the 13.4MHz case.

## 4.4 Quartz Frequency Calculation

As described in Section 3.4.3 the operating range of the on-chip VCO is 820 to 860 MHz with a nominal center frequency of 840MHz. This signal is divided by 2 before applied to the mixer in case of operation at 434 MHz. This local oscillator signal can be used to downconvert the RF signals both with high- or low-side injection at the mixer. The resulting receive frequency ranges then extend between 810 and 870MHz or between 400 and 440MHz. Low-side injection of the local oscillator has to be used for receive frequencies between 840 and 870MHz as well as high-side injection for receive frequencies below 840MHz. Corresponding to that in the 400MHz region low-side injection is applicable for receive frequencies above 420MHz, high-side injection below this frequency. Therefore for operation both in the 868 and the 434 MHz ISM bands low-side injection of the local oscillator has to be used. Then the local oscillator frequency is calculated by subtracting the IF frequency (10.7 MHz) from the RF frequency (434 or 868 MHz). Please note that no sign-inversion occurs in case of reception and demodulation of FSK-modulated signals.

The overall division ratios in the PLL are 64 or 128 in case of operation at 868 MHz or 32 and 64 in case of operation at 434 MHz, depending on the crystal frequency used as shown below. The quartz frequency in case of low-side injection may be calculated by using the following formula:

$$f_{QU} = (f_{RF} - 10.7) / r$$

with  $f_{RF}$  receive frequency

 $f_{10}$  local oscillator (PLL) frequency ( $f_{RF}$  - 10.7)

 $f_{OU}$  quartz oscillator frequency

r ratio of local oscillator (PLL) frequency and quartz frequency as shown in the subsequent table

Table 4-1 Dependence of PLL Overall Division Ratio on FSEL and CSEL					
FSEL	CSEL	Ratio $r = (f_{LO}/f_{QU})$			
open	open	64			
open	GND	32			
GND	open	128			
GND	GND	64			

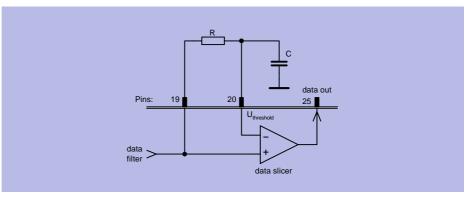
:

$$\begin{split} f_{\text{QU}} &= (868.4MHz - 10.7MHz)/64 = 13.40156MHz \\ f_{\text{QU}} &= (868.4MHz - 10.7MHz)/128 = 6.7008\,MHz \\ f_{\text{QU}} &= (434.2MHz - 10.7MHz)/32 = 13.23437\,MHz \\ f_{\text{OU}} &= (434.2MHz - 10.7MHz)/64 = 6.6172\,MHz \end{split}$$



#### 4.5 Data Slicer Threshold Generation

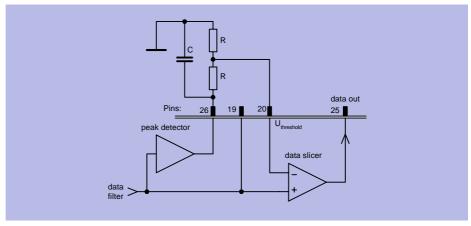
The threshold of the data slicer can be generated using an external R-C integrator as shown in Figure 4-5. The cut-off frequency of the R-C integrator has to be lower than the lowest frequency appearing in the data signal. In order to keep distortion low, the minimum value for R is  $20k\Omega$ .



Data\_slice1.wmf

Figure 4-5 Data Slicer Threshold Generation with External R-C Integrator

In case of ASK operation another possibility for threshold generation is to use the peak detector in connection with two resistors and one capacitor as shown in the following figure. The component values are depending on the coding scheme and the protocol used.



Data slice2.wmf

Figure 4-6 Data Slicer Threshold Generation Utilising the Peak Detector



### 4.6 ASK/FSK Switch Functional Description

The TDA5210 is containing an ASK/FSK switch which can be controlled via Pin 15 (MSEL). This switch is actually consisting of 2 operational amplifiers that are having a gain of 1 in case of the ASK amplifier and a gain of 11 in case of the FSK amplifier in order to achieve an appropriate demodulation gain characteristic. In order to compensate for the DC-offset generated especially in case of the FSK PLL demodulator there is a feedback connection between the threshold voltage of the bit slicer comparator (Pin 20) to the negative input of the FSK switch amplifier. This is shown in the following figure.

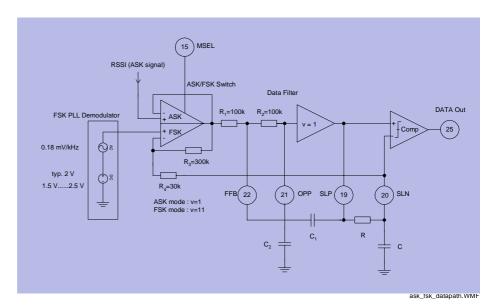


Figure 4-7 ASK/FSK mode datapath

#### 4.6.1 FSK Mode

The FSK datapath has a bandpass characterisite due to the feedback shown above (highpass) and the data filter (lowpass). The lower cutoff frequency f2 is determined by the external RC-combination. The upper cutoff frequency f3 is determined by the data filter bandwidth.

The demodulation gain of the FSK PLL demodulator is  $140\mu V/kHz$ . This gain is increased by the gain v of the FSK switch, which is 11. Therefore the resulting dynamic gain of this circuit is 2mV/kHz within the bandpass. The gain for the DC content of FSK signal remains at  $140\mu V/kHz$ . The cutoff frequencies of the bandpass have to be chosen such that the spectrum of the data signal is influenced in an acceptable amount.

In case that the user data is containing long sequences of logical zeroes the effect of the drift-off of the bit slicer threshold voltage can be lowered if the offset voltage inherent at the negative input of the slicer comparator (Pin20) is used. The comparator has no hysteresis built in.



This offset voltage is generated by the bias current of the negative input of the comparator (i.e. 20nA) running over the external resistor R. This voltage raises the voltage appearing at pin 20 (e.g. 1mV with R =  $100k\Omega$ ). In order to obtain benefit of this asymmetrical offset for the demodulation of long zeros the lower of the two FSK frequencies should be chosen in the transmitter as the zerosymbol frequency.

In the following figure the shape of the above mentioned bandpass is shown.

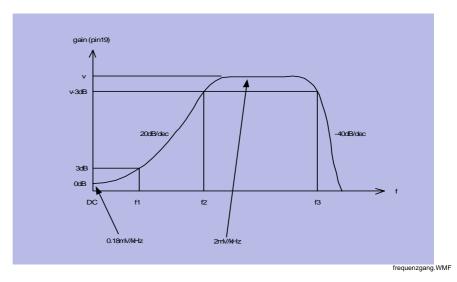


Figure 4-8 Frequency characterstic in case of FSK mode

The cutoff frequencies are calculated with the following formulas:

$$f_1 = \frac{1}{2\pi \frac{R \cdot 330k\Omega}{R + 330k\Omega} \cdot C}$$

$$f_2 = v \cdot f_1 = 11 \cdot f_1$$

$$f_3 = f_{3dR}$$

f<sub>3</sub> is the 3dB cutoff frequency of the data filter - see Section 4.2.

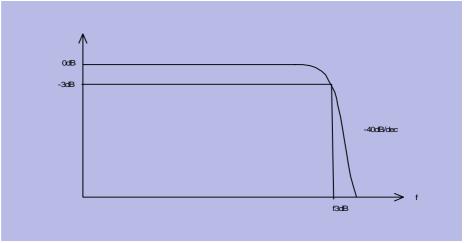
Example:

$$R = 100k\Omega$$
,  $C = 47nF$ 

This leads  $tof_1 = 44Hzandf_2 = 485Hz$ 

#### 4.6.2 ASK Mode

In case the receiver is operated in ASK mode the datapath frequency charactersitic is dominated by the data filter alone, thus it is lowpass shaped. The cutoff frequency is determined by the external capacitors C12 and C14 and the internal 100k resistors as described in Section 4.2



freq\_ask.WMF

Figure 4-9 Frequency charcteristic in case of ASK mode



# 4.7 Principle of the Precharge Circuit

In case the data slicer threshold shall be generated with an external RC network as described in Section 4.5 it is necessary to use large values for the capacitor C attached to the **SLN** pin (pin 20) in order to achieve long time constants. This results also from the fact that the choice of the value for R connected between the **SLP** and **SLN** pins (pins 19 and 20) is limited by the  $330k\Omega$  resistor appearing in parallel to R as can be seen in Figure 4-7. Apart from this a resistor value of  $100k\Omega$  leads to a voltage offset of 1mv at the comparator input as described in Section 4.6.1. The resulting startup time constant  $\tau_1$  can be calculated with:

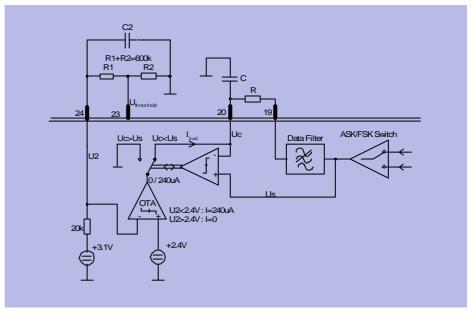
$$\tau_1 = (R // 330k\Omega) \cdot C$$

In case R is chosen to be  $100k\Omega$  and C is chosen as 47nF this leads to

$$\tau_1 = (100 k\Omega /\!/ 330 k\Omega) \cdot 47 nF = 77 k\Omega \cdot 47 nF = 3.6 ms$$

When the device is turned on this time constant dominates the time necessary for the device to be able to demodulate data properly. In the powerdown mode the capacitor is only discharged by leakage currents.

In order to reduce the turn-on time in the presence of large values of C a precharge circuit was included in the TDA5210 as shown in the following figure.



precharge.WMF

Figure 4-10 Principle of the precharge circuit

This circuit charges the capacitor C with an inrush current  $I_{load}$  of typically 220µA for a duration of  $T_2$  until the voltage  $U_c$  appearing on the capacitor is equal to the voltage  $U_s$  at the input of the data filter. This voltage is limited to 2.5V. As soon as these voltages are equal or the duration  $T_2$  is exceeded the precharge circuit is disabled.

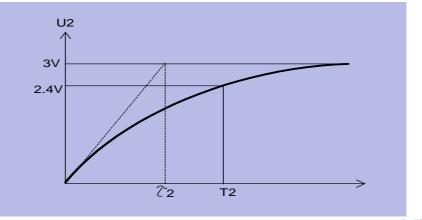
 $\tau_2$  is the time constant of the charging process of C which can be calculated as

$$\tau_2 \approx 20 k\Omega \cdot C2$$

as the sum of R1 and R2 is sufficiently large and thus can be neglected. T2 can then be calculated according to the following formula:

$$T_2 = \tau_2 \ln \left( \frac{1}{1 - \frac{2.4V}{3V}} \right) \approx \tau_2 \cdot 1.6$$

The voltage transient during the charging of C2 is shown in the following figure:



e-fkt1.WMF

Figure 4-11 Voltage appearing on C2 during precharging process

The voltage appearing on the capacitor C connected to pin 20 is shown in the following figure. It can be seen that due to the fact that it is charged by a constant current source it exhibits is a linear increase in voltage which is limited to  $U_{Smax} = 2.5V$  which is also the approximate operating point of the data filter input. The time constant appearing in this case can be denoted as T3, which can be calculated with

$$T3 = \frac{U_{\text{Smax}} \cdot C}{220 \mu A} = \frac{2.5 \text{ V}}{220 \mu A} \cdot C$$

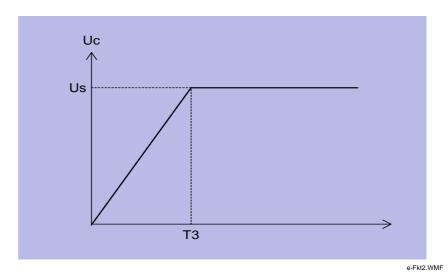


Figure 4-12 Voltage transient on capacitor C attached to pin 20

As an example the choice of C2 = 22nF and C = 47nF yields

 $\tau_2 = 0.44 ms$ 

 $T_2 = 0.71 ms$ 

 $T_3 = 0.53 ms$ 

This means that in this case the inrush current could flow for a duration of 0.64ms but stops already after 0.49ms when the  $U_{Smax}$  limit has been reached. T3 should always be chosen to be shorter than T2.

It has to be noted finally that during the turn-on duration T2 the overall device power consumption is increased by the 220µA needed to charge C.

The precharge circuit may be disabled if C2 is not equipped. This yields a T2 close to zero. Note that the sum of R4 and R5 has to be  $600k\Omega$  in order to produce 3V at the THRES pin as this voltage is internally used also as the reference for the FSK demodulator.

# 5 Reference

Contents of this Chapter				
5.1	Electrical Data	5-2		
5.2	Test Circuit	5-12		
5.3	Test Board Layouts	5-13		
5 1	Rill of Materials	5_15		



Reference

# 5.1 Electrical Data

# 5.1.1 Absolute Maximum Ratings



#### **WARNING**

The maximum ratings may not be exceeded under any circumstances, not even momentarily and individually, as permanent damage to the IC will result.

Tabl	Table 5-1 Absolute Maximum Ratings, Ambient temperature T <sub>AMB</sub> =-40°C + 105°C					
#	Parameter	Symbol	Limit Values		Unit	Remarks
			min	max		
1	Supply Voltage	Vs	-0.3	5.5	V	
2	Junction Temperature	Тj	-40	+150	°C	
3	Storage Temperature	T <sub>s</sub>	-40	+125	°C	
4	Thermal Resistance	R <sub>thJA</sub>		114	K/W	
5	ESD integrity, all pins excl. Pins 1,3, 6, 28 ESD integrity Pins 1,3,6,28	V <sub>ESD</sub>		+2 +1.5	kV kV	HBM according to MIL STD 883D, method 3015.7



## 5.1.2 Operating Range

Within the operational range the IC operates as explained in the circuit description. The AC/DC characteristic limits are not guaranteed. Currents flowing into the device are denoted as positive currents and v.v.

Supply voltage: VCC = 4.5V .. 5.5V

Tal	Table 5-2 Operating Range, Ambient temperature T <sub>AMB</sub> = -40°C + 105°C							
#	Parameter	Symbol	Limit \	Values	Unit	Test Conditions	L	Item
			min	max				
1	Supply Current	ISF 868 ISF 434 ISA 868 ISA 434	4.1 3.9 3.4 3.2	7.7 7.5 7 6.8	mA mA mA mA	$\begin{split} f_{RF} &= 868 \text{MHz, FSK Mode} \\ f_{RF} &= 434 \text{MHz, FSK Mode} \\ f_{RF} &= 868 \text{MHz, ASK Mode} \\ f_{RF} &= 434 \text{MHz, ASK Mode} \end{split}$		
2	Receiver Input Level ASK FSK, frequ. dev. ± 50kHz	RF <sub>in</sub>	-106 -100	-13 -13	dBm dBm	@ source impedance $50\Omega$ , BER 2E-3, average power level, Manchester encoded datarate 4kBit, 280kHz IF Bandwidth	•	
3	LNI Input Frequency	f <sub>RF</sub>	400/ 810	440/ 870	MHz			
4	MI/X Input Frequency	f <sub>MI</sub>	400/ 810	440/ 870	MHz			
5	3dB IF Frequency Range ASK FSK	f <sub>IF -3dB</sub>	5 10.4	23 11	MHz		•	
6	Powerdown Mode On	PWDN <sub>ON</sub>	0	0.8	V			
7	Powerdown Mode Off	PWDN <sub>OFF</sub>	2	V <sub>S</sub>	V			
8	Gain Control Voltage, LNA high gain state	V <sub>THRES</sub>	2.8	V <sub>S</sub>	V			
9	Gain Control Voltage, LNA low gain state	V <sub>THRES</sub>	0	0.7	V			

<sup>■</sup> This value is guaranteed by design.



Parameter

Reference

## 5.1.3 AC/DC Characteristics at T<sub>AMB</sub> = 25°C

**Limit Values** 

Table 5-3 AC/DC Characteristics with  $T_A$  25 °C,  $V_{VCC}$  = 4.5 ... 5.5 V

Symbol

AC/DC characteristics involve the spread of values guaranteed within the specified voltage and ambient temperature range. Typical characteristics are the median of the production. Currents flowing into the device are denoted as positive currents and vice versa.

Unit Test Conditions

	Parameter	Symbol	L	₋imit vaiu	es	Unit	lest Conditions	L	item
			min	typ	max				
Su	pply								
Su	pply Current								
1	Supply current, standby mode	I <sub>S PDWN</sub>		50	100	nA	Pin 27 (PDWN) open or tied to 0 V		
2	Supply current, device operating in 868 MHz range, FSK mode	I <sub>SF 868</sub>	5.1	5.9	6.7	mA	Pin 11 (FSEL) tied to GND, Pin 15 (MSEL) tied to GND		
3	Supply current, device operating in 434 MHz range, FSK mode	I <sub>SF 434</sub>	4.9	5.7	6.5	mA	Pin 11 (FSEL) open, Pin 15 (MSEL) tied to GND		
4	Supply current, device operating in 868 MHz range, ASK mode	I <sub>SA 868</sub>	4.4	5.2	6	mA	Pin 11 (FSEL) tied to GND, Pin 15 (MSEL) open		
5	Supply current, device operating in 434 MHz range, ASK mode	I <sub>SA 434</sub>	4.2	5	5.8	mA	Pin 11 (FSEL) open, Pin 15 (MSEL) open		
LN									
Siç	gnal Input LNI (PIN 3),  V <sub>T</sub>	HRES > 2.8V,	high gaiı	n mode					
1	Average Power Level at BER = 2E-3 (Sensitivity) ASK	RF <sub>in</sub>		-110		dBm	Manchester encoded datarate 4kBit, 280kHz IF Bandwidth	•	
2	Average Power Level at BER = 2E-3 (Sensitivity) FSK	RF <sub>in</sub>		-103		dBm	Manchester enc. datarate 4kBit, 280kHz IF Bandw., ± 50kHz pk. dev.	•	
3	Input impedance, f <sub>RF</sub> =434 MHz	S <sub>11 LNA</sub>	8.0	373 / -34.7	deg			•	
4	Input impedance, f <sub>RF</sub> =869 MHz	S <sub>11 LNA</sub>	0.7	738 / -73.5	deg			•	
5	Input level @ 1dB compression	P1dB <sub>LNA</sub>		-15		dBm		•	
6	Input 3 <sup>rd</sup> order intercept point f <sub>RF</sub> =434 MHz	IIP3 <sub>LNA</sub>		-10		dBm	matched input	٠	
7	Input 3 <sup>rd</sup> order intercept point f <sub>RF</sub> =869 MHz	IIP3 <sub>LNA</sub>		-14		dBm	matched input	•	



Ta	ble 5-3 AC/DC Character	istics with T <sub>A</sub>	25 °C, V	vcc = 4.5	5.5 V (c	ontinue	d)		
	Parameter	Symbol	L	₋imit Valu	es	Unit	Test Conditions	L	Item
			min	typ	max				
8	LO signal feedthrough at antenna port	LO <sub>LNI</sub>			-73	dBm		r	
Sig	gnal Output LNO (PIN 6),	V <sub>THRES</sub> > 2.8	V, high g	ain mode					
1	Gain f <sub>RF</sub> =434 MHz	S <sub>21 LNA</sub>	1.5	509 / 138.2	deg			•	
2	Gain f <sub>RF</sub> =869 MHz	S <sub>21 LNA</sub>	1.4	19 / 101.7	' deg				
3	Output impedance, f <sub>RF</sub> =434 MHz	S <sub>22 LNA</sub>	0.8	386 / -12.9	deg			•	
4	Output impedance, f <sub>RF</sub> =869 MHz	S <sub>22 LNA</sub>	0.8	366 / -24.2	deg			•	
5	Voltage Gain Antenna to IFO f <sub>RF</sub> =434 MHz	G <sub>AntMI</sub>		42		dB			
6	Voltage Gain Antenna to IFO f <sub>RF</sub> =869 MHz	G <sub>AntMI</sub>		40		dB			
Sig	nal Input LNI, V <sub>THRES</sub> =	GND, low gai	n mode						
1	Input impedance, f <sub>RF</sub> =434 MHz	S <sub>11 LNA</sub>	0.8	373 / -34.7	deg			•	
2	Input impedance, f <sub>RF</sub> =869 MHz	S <sub>11 LNA</sub>	0.7	738 / -73.5	deg			•	
3	Input level @ 1dB C. P f <sub>RF</sub> = 434 MHz	P1dB <sub>LNA</sub>		-18		dBm	matched input	•	
4	Input level @ 1dB C. P f <sub>RF</sub> = 869 MHz	P1dB <sub>LNA</sub>		-6		dBm	matched input	•	
5	Input 3 <sup>rd</sup> order intercept point f <sub>RF</sub> =434 MHz	IIP3 <sub>LNA</sub>		-10		dBm	matched input	ľ	
6	Input 3 <sup>rd</sup> order intercept point f <sub>RF</sub> =869 MHz	IIP3 <sub>LNA</sub>		-5		dBm	matched input	•	
Sig	nal Output LNO, V <sub>THRES</sub>	s = GND, low ថ្	gain mod	le					
1	Gain f <sub>RF</sub> =434 MHz	S <sub>21 LNA</sub>	0.1	83 / 140.6	deg			•	
2	Gain f <sub>RF</sub> =869 MHz	S <sub>21 LNA</sub>	0.1	179 / 109.1	Ideg			•	
3	Output impedance, f <sub>RF</sub> =434 MHz	S <sub>22 LNA</sub>	0.8	397 / -13.6	deg			•	
4	Output impedance, f <sub>RF</sub> =869 MHz	S <sub>22 LNA</sub>	0.8	368 / -26.3	deg			•	
5	Voltage Gain Antenna to MI f <sub>RF</sub> =434 MHz	G <sub>AntMI</sub>		22		dB			
6	Voltage Gain Antenna to MI f <sub>RF</sub> =869 MHz	G <sub>AntMI</sub>		19		dB			



	Parameter	Symbol	L	imit Valu	es	Unit	Test Conditions	L	Item
		•	min	typ	max				
Siç	gnal 3VOUT (PIN 24)								
1	Output voltage	V <sub>3VOUT</sub>	2.9	3.1	3.3	V	3VOUT Pin open		
2	Current out	I <sub>3VOUT</sub>	-3	-5	-10	μΑ	see Section 4.1		
Sig	gnal THRES (PIN 23)								
1	Input Voltage range	$V_{THRES}$	0		V <sub>S</sub> -1V	V	see Section 4.1		
2	LNA low gain mode	$V_{THRES}$	0			V			
3	LNA high gain mode	V <sub>THRES</sub>	2.8	3	V <sub>S</sub>	V	or shorted to Pin 24		
4	Current in	I <sub>THRES_in</sub>		5		nA			
Siç	gnal TAGC (PIN 4)								
1	Current out, LNA low gain state	I <sub>TAGC_out</sub>	-3.6	-4.2	-5	μA	RSSI > V <sub>THRES</sub>		
2	Current in, LNA high gain state	$V_{TAGC\_in}$	1	1.6	2.2	μA	RSSI>V <sub>THRES</sub>		
MIXER									
Siç	gnal Input MI/MIX (PINS 8	<b>/</b> 9)							
1	Input impedance, f <sub>RF</sub> =434 MHz	S <sub>11 MIX</sub>	0.9	942 / -14.4	deg			•	
2	Input impedance, f <sub>RF</sub> =869 MHz	S <sub>11 MIX</sub>	0.9	918 / -28.1	deg			•	
3	Input 3 <sup>rd</sup> order intercept point f <sub>RF</sub> =434 MHz	IIP3 <sub>MIX</sub>		-28		dBm		•	
4	Input 3 <sup>rd</sup> order intercept point f <sub>RF</sub> =869 MHz	IIP3 <sub>MIX</sub>		-26		dBm		•	
Sig	gnal Output IFO (PIN 12)								
1	Output impedance	$Z_{IFO}$		330		Ω		•	
2	Conversion Voltage Gain f <sub>RF</sub> =434 MHz	G <sub>MIX</sub>		+19		dB			
3	Conversion Voltage Gain f <sub>RF</sub> =869 MHz	G <sub>MIX</sub>		+18		dB			
LIN	MITER								
Siç	gnal Input LIM/X (PINS 17	/18)							
1	Input Impedance	$Z_{LIM}$	264	330	396	Ω		•	
2	RSSI dynamic range	DR <sub>RSSI</sub>	60		80	dB			
3	RSSI linearity	LIN <sub>RSSI</sub>		±1		dB		•	
4	Operating frequency (3dB points)	$f_{LIM}$	5	10.7	23	MHz		•	



	Parameter	Symbol		Limit Valu	es	Unit	Test Conditions	L	Item
			min	typ	max				
DΑ	TA FILTER								
1	Useable bandwidth	BW <sub>BB FILT</sub>			100	kHz			
2	RSSI Level at Data Filter Output SLP, RF <sub>IN</sub> =-103dBm	RSSI <sub>low</sub>	0.3		1	V	LNA in high gain mode		
3	RSSI Level at Data Filter Output SLP, RF <sub>IN</sub> =-30dBm	RSSI <sub>high</sub>	1.8		3	V	LNA in high gain mode		
Slicer, Signal Output DATA (PIN 25)									
1	Maximum Datarate	DR <sub>max</sub>			100	kBps	NRZ, 20pF capacitive loading	·	
2	LOW output voltage	V <sub>SLIC_L</sub>	0		0.1	V			
3	HIGH output voltage	V <sub>SLIC_H</sub>	V <sub>S</sub> - 1.3V	V <sub>S</sub> -1V	V <sub>S</sub> - 0.7V	V			
Slicer, Signal Output DATA (PIN 20)									
1	Precharge Current Out	I <sub>PCH_SLN</sub>	-100	-220	-300	μA	see Section 4.7		
PE	AK DETECTOR								
Siç	gnal Output PDO (PIN 26)								
1	Load current	I <sub>load</sub>	-600	-950	-1300	μA			
2	Leakage current	I <sub>leakage</sub>	0	200	1000	nA			
CR	RYSTAL OSCILLATOR								
Się	gnals CRSTL1, CRSTL 2,	(PINS 1/28)							
1	Operating frequency	fCRSTL	6		14	MHz	fundamental mode, series resonance		
2	Input Impedance @ ~6MHz	Z <sub>1-28</sub>		-825 +j695		Ω		٠	
3	Input Impedance @ ~13MHz	Z <sub>1-28</sub>		-600 +j1010		Ω		•	
4	Serial Capacity @ ~6MHz	C <sub>S 6</sub> =C1		8.9		pF			
5	Serial Capacity @ ~13MHz	C <sub>S13</sub> =C1		5.9		pF			
AS	K/FSK Signal Switch								
Siç	gnal MSEL (PIN 15)								
1	ASK Mode	$V_{MSEL}$	1.4		4	V	or open		
2	FSK Mode	V <sub>MSEL</sub>	0		0.2	V			



та	ble 5-3 AC/DC Character								
	Parameter	Symbol		₋imit Valu		Unit	Test Conditions	L	Item
			min	typ	max				
FS	K DEMODULATOR								
1	Demodulation Gain	G <sub>FMDEM</sub>	85	140	225	μV/ kHz			
2	Useable IF Bandwidth	BW <sub>IFPLL</sub>	10.2	10.7	11.2	MHz			
POWER DOWN MODE									
Sig	gnal PDWN (PIN 27)								
1	Powerdown Mode On	PWDN <sub>ON</sub>	0		0.8	V			
2	Powerdown Mode Off	PWDN <sub>Off</sub>	2.8		Vs	V			
3	Input bias current PDWN	I <sub>PDWN</sub>		19		uA	Power On Mode		
4	Start-up Time until valid signal is detected at IF	T <sub>SU</sub>			1	ms			
VC	O MULTIPLEXER								
Siç	gnal FSEL (PIN 11)								
1	f <sub>RF</sub> range 434 MHz	V <sub>FSEL</sub>	1.4		4	V	or open		
2	f <sub>RF</sub> range 869 MHz	$V_{FSEL}$	0		0.2	V			
3	Output bias current FSEL	I <sub>FSEL</sub>	-160	-200	-240	μA	FSEL tied to GND		
PL	L DIVIDER								
Siç	gnal CSEL (PIN 16)								
1	f <sub>CRSTL</sub> range 6.xxMHz	V <sub>CSEL</sub>	1.4		4	V	or open		
2	f <sub>CRSTL</sub> range 13.xxMHz	V <sub>CSEL</sub>	0		0.2	V			
3	Input bias current CSEL	I <sub>CSEL</sub>	-3	-5	-7	μA	CSEL tied to GND		

Measured only in lab.



## 5.1.4 AC/DC Characteristics at $T_{AMB} = -40$ to $105^{\circ}C$

Currents flowing into the device are denoted as positive currents and vice versa

	Parameter	Symbol	L	_imit Valu	es	Unit	Test Conditions	L	Item
			min	typ	max				
Su	pply								
Su	pply Current								
1	Supply current, standby mode	I <sub>S PDWN</sub>		50	400	nA	Pin 27 (PDWN) open or tied to 0 V		
2	Supply current, device operating in 868 MHz range, FSK mode	I <sub>SF 868</sub>	4.1	5.9	7.7	mA	Pin 11 (FSEL) tied to GND, Pin 15 (MSEL) tied to GND		
3	Supply current, device operating in 434 MHz range, FSK mode	I <sub>SF 434</sub>	3.9	5.7	7.5	mA	Pin 11 (FSEL) open, Pin 15 (MSEL) tied to GND		
4	Supply current, device operating in 868 MHz range, ASK mode	I <sub>SA 868</sub>	3.4	5.2	7	mA	Pin 11 (FSEL) tied to GND, Pin 15 (MSEL) open		
5	Supply current, device operating in 434 MHz range, ASK mode	I <sub>SA 434</sub>	3.2	5	6.8	mA	Pin 11 (FSEL) open, Pin 15 (MSEL) open		
Siç	gnal 3VOUT (PIN 24)								
1	Output voltage	V <sub>3VOUT</sub>	2.9	3.1	3.3	V	3VOUT Pin open		
2	Current out	I <sub>3VOUT</sub>	-3	-5	-10	μΑ	see Section 4.1		
Sig	gnal THRES (PIN 23)								
1	Input Voltage range	V <sub>THRES</sub>	0		V <sub>S</sub> -1V	V	see Section 4.1		
2	LNA low gain mode	$V_{THRES}$	0		0.3	V			
3	LNA high gain mode	V <sub>THRES</sub>	3		V <sub>S</sub>	V	or shorted to Pin 24		
4	Current in	I <sub>THRES_in</sub>		5		nA			
Sig	gnal TAGC (PIN 4)								
1	Current out, LNA low gain state	I <sub>TAGC_out</sub>	-1	-4.2	-8	μA	RSSI > V <sub>THRES</sub>		
2	Current in, LNA high gain state	V <sub>TAGC_in</sub>	0.5	1.5	5	μA	RSSI>V <sub>THRES</sub>		
MI	XER								
1	Conversion Voltage Gain f <sub>RF</sub> =434 MHz	G <sub>MIX</sub>		+19		dB			
2	Conversion Voltage Gain f <sub>RF</sub> =869 MHz	G <sub>MIX</sub>		+18		dB			
LIN	MITER								
Sig	gnal Input LIM/X (PINS 17	'/18)							
1	RSSI dynamic range	DR <sub>RSSI</sub>	60		80	dB			



	Parameter	Symbol	ı	Limit Valu	es	Unit	Test Conditions	L	Item
			min	typ	max				
DΑ	ATA FILTER								
2	RSSI Level at Data Filter Output SLP, RF <sub>IN</sub> =-103dBm	RSSI <sub>low</sub>	0.3		1	V	LNA in high gain mode		
3	RSSI Level at Data Filter Output SLP, RF <sub>IN</sub> =-30dBm	RSSI <sub>high</sub>	1.8		3	V	LNA in high gain mode		
Sli	icer, Signal Output DATA	(PIN 25)							
1	Maximum Datarate	DR <sub>max</sub>			100	kBps	NRZ, 20pF capacitive loading	•	
2	LOW output voltage	V <sub>SLIC_L</sub>	0		0.1	V			
3	HIGH output voltage	V <sub>SLIC_H</sub>	V <sub>S</sub> - 1.5V	V <sub>S</sub> -1V	V <sub>S</sub> - 0.5V	V			
Sli	icer, Signal Output DATA	(PIN 20)							
1	Precharge Current Out	I <sub>PCH_SLN</sub>	-100	-220	-300	μΑ	see Section 4.7		
PE	EAK DETECTOR								
Siç	gnal Output PDO (PIN 26)								
1	Load current	I <sub>load</sub>	-400	-850	-1400	μΑ			
2	Leakage current	I <sub>leakage</sub>	0	700	2000	nA			
C.	OVETAL OCCULATOR								
UГ	RISTAL USCILLATUR								
	RYSTAL OSCILLATOR gnals CRSTL1, CRSTL 2,	(PINS 1/28)							
		(PINS 1/28)	6		14	MHz	fundamental mode, series resonance		
Sig 1	gnals CRSTL1, CRSTL 2, Operating frequency		6		14	MHz			
Sig 1	gnals CRSTL1, CRSTL 2, Operating frequency SK/FSK Signal Switch		6		14	MHz			
Sig 1	gnals CRSTL1, CRSTL 2, Operating frequency		6		14	MHz			
Sig 1 AS Sig 1	gnals CRSTL1, CRSTL 2, Operating frequency  SK/FSK Signal Switch gnal MSEL (PIN 15)	<sup>f</sup> CRSTL					series resonance		
Sig 1 AS Sig 1	gnals CRSTL1, CRSTL 2, Operating frequency  SK/FSK Signal Switch gnal MSEL (PIN 15)  ASK Mode  FSK Mode	fcrstl V <sub>MSEL</sub>	1.4		4	V	series resonance		
Sig 1 AS Sig 1 2	gnals CRSTL1, CRSTL 2, Operating frequency  SK/FSK Signal Switch gnal MSEL (PIN 15)  ASK Mode  FSK Mode  SK DEMODULATOR	fCRSTL  VMSEL  VMSEL	1.4	140	4 0.2	V	series resonance		
Sig 1 AS Sig 1 2	gnals CRSTL1, CRSTL 2, Operating frequency  SK/FSK Signal Switch gnal MSEL (PIN 15)  ASK Mode  FSK Mode	fcrstl V <sub>MSEL</sub>	1.4	140	4	V	series resonance		
Sig 1 AS Sig 1	gnals CRSTL1, CRSTL 2, Operating frequency  SK/FSK Signal Switch gnal MSEL (PIN 15)  ASK Mode  FSK Mode  SK DEMODULATOR	fCRSTL  VMSEL  VMSEL	1.4	140	4 0.2	V V	series resonance		
Sig 1 AS Sig 1 2	gnals CRSTL1, CRSTL 2, Operating frequency  SK/FSK Signal Switch gnal MSEL (PIN 15)  ASK Mode  FSK Mode  SK DEMODULATOR Demodulation Gain	f <sub>CRSTL</sub> V <sub>MSEL</sub> V <sub>MSEL</sub> G <sub>FMDEM</sub>	1.4		4 0.2 245	V V µV/ kHz	series resonance		
Sig 1 AS Sig 1 2 FS 1	gnals CRSTL1, CRSTL 2, Operating frequency  SK/FSK Signal Switch gnal MSEL (PIN 15)  ASK Mode  FSK Mode  SK DEMODULATOR  Demodulation Gain  Useable IF Bandwidth	f <sub>CRSTL</sub> V <sub>MSEL</sub> V <sub>MSEL</sub> G <sub>FMDEM</sub>	1.4		4 0.2 245	V V µV/ kHz	series resonance		
Sig 1 AS Sig 1 2 PC	gnals CRSTL1, CRSTL 2, Operating frequency  SK/FSK Signal Switch gnal MSEL (PIN 15)  ASK Mode  FSK Mode  SK DEMODULATOR  Demodulation Gain  Useable IF Bandwidth  DWER DOWN MODE	f <sub>CRSTL</sub> V <sub>MSEL</sub> V <sub>MSEL</sub> G <sub>FMDEM</sub>	1.4		4 0.2 245	V V µV/ kHz	series resonance		
Sig 1 AS Sig 1 2 PC Sig	gnals CRSTL1, CRSTL 2, Operating frequency  SK/FSK Signal Switch gnal MSEL (PIN 15)  ASK Mode  FSK Mode  SK DEMODULATOR  Demodulation Gain  Useable IF Bandwidth  DWER DOWN MODE gnal PDWN (PIN 27)	FCRSTL  VMSEL  VMSEL  GFMDEM  BWIFPLL	1.4 0 105 10.2		4 0.2 245 11.2	V V V µV/ kHz MHz	series resonance		

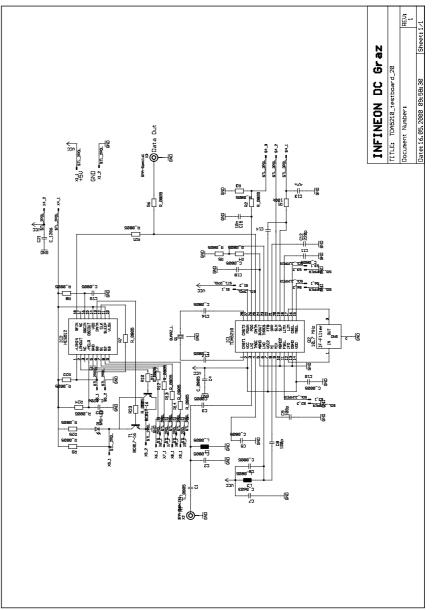


Та	ble 5-4 AC/DC Character	ristics with T <sub>A</sub>	<sub>MB</sub> = -40°	°C + 10	5°C, V <sub>VCC</sub>	= 4.5	5.5 V		
	Parameter	Symbol	L	imit Valu	es	Unit	Test Conditions	L	Item
			min	typ	max				
VC	VCO MULTIPLEXER								
Sig	gnal FSEL (PIN 11)								
1	f <sub>RF</sub> range 434 MHz	$V_{FSEL}$	1.4		4	V	or open		
2	f <sub>RF</sub> range 869 MHz	$V_{FSEL}$	0		0.2	V			
3	Output bias current FSEL	I <sub>FSEL</sub>	-110	-200	-340	μA	FSEL tied to GND		
PL	L DIVIDER								
Siç	gnal CSEL (PIN 16)								
1	f <sub>CRSTL</sub> range 6.xxMHz	V <sub>CSEL</sub>	1.4		4	V	or open		
2	f <sub>CRSTL</sub> range 13.xxMHz	V <sub>CSEL</sub>	0		0.2	V			
3	Input bias current CSEL	I <sub>CSEL</sub>	-3	-5	-7	μΑ	CSEL tied to GND		



#### 5.2 Test Circuit

The device performance parameters marked with in Section 5.1.3 were measured on an Infineon evaluation board. This evaluation board can be obtained together with evaluation boards of the accompanying transmitter device TDA5100 in an evaluation kit that may be ordered on the INFINEON RKE Webpage www.infineon.com/rke. In case a matching codeword is received, decoded and accepted by the decoder the on-board LED will turn on. This signal is also accessible on a 2-pole pin connector and can be used for simple remote-control applications. More information on the kit is available on request.

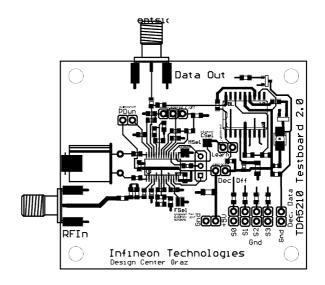


TDA5210\_testboard\_20\_schematic.WMF

Figure 5-1 Schematic of the Evaluation Board

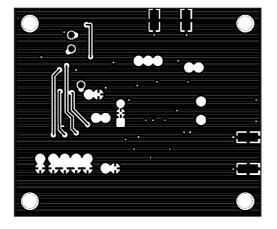


## 5.3 Test Board Layouts



tda5210\_testboard\_20\_top.WMF

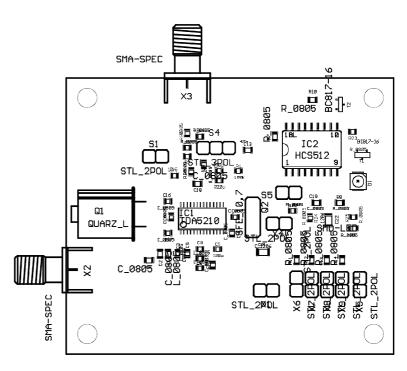
Figure 5-2 Top Side of the Evaluation Board



tda5210\_testboard\_20\_bot.WMF

Figure 5-3 Bottom Side of the Evaluation Board





tda5210\_testboard\_20\_plc.EMF

Figure 5-4 Component Placement on the Evaluation Board



## 5.4 Bill of Materials

The following components are necessary for evaluation of the TDA5210 without use of a Microchip HCS512 decoder.

Table 5-5 Bill of	of Materials	
Ref	Value	Specification
R1	100kΩ	0805, ± 5%
R2	100kΩ	0805, ± 5%
R3	820kΩ	0805, ± 5%
R4	240kΩ	0805, ± 5%
R5	360kΩ	0805, ± 5%
R6	10kΩ	0805, ± 5%
L1	434 MHz: 15nH 869 MHz: 3.3nH	Toko, PTL2012-F15N0G Toko, PTL2012-F3N3C
L2	434 MHz: 8.2pF 869 MHz: 3.9nH	0805, COG, ± 0.1pF Toko, PTL2012-F3N9C
C1	1pF	0805, COG, ± 0.1pF
C2	434 MHz: 4.7pF 869 MHz: 3.9pF	0805, COG, ± 0.1pF 0805, COG, ± 0.1pF
С3	434 MHz: 6.8pF 869 MHz: 5.6pF	0805, COG, ± 0.1pF 0805, COG, ± 0.1pF
C4	100pF	0805, COG, ± 5%
C5	47nF	1206, X7R, ± 10%
C6	434 MHz: 10nH 869 MHz: 3.9pF	Toko, PTL2012-F10N0G 0805, COG, ± 0.1pF
C7	100pF	0805, COG, ± 5%
C8	434 MHz: 33pF 869 MHz: 22pF	0805, COG, ± 5% 0805, COG, ± 5%
C9	100pF	0805, COG, ± 5%
C10	10nF	0805, X7R, ± 10%
C11	10nF	0805, X7R, ± 10%
C12	220pF	0805, COG, ± 5%
C13	47nF	0805, X7R, ± 10%
C14	470pF	0805, COG, ± 5%
C15	47nF	0805, X7R, ± 5%
C16	8.2pF	0805, COG, ± 0.1pF
C17	22pF	0805, COG, ± 1%
C18	22nF	0805, X7R, ± 5%
Q1	(f <sub>RF</sub> – 10.7MHz)/32 or (f <sub>RF</sub> – 10.7MHz)/64	HC49/U, fundamental mode, CL = 12pF, e.g. 434.2MHz: Jauch Q 13,23437-S11-1323-12-10/20 e.g. 868.4MHz: Jauch Q 13,40155-S11-1323-12-10/20



Q2	SFE10.7MA5-A or SKM107M1-A20-10	Murata Toko
X2, X3	142-0701-801	Johnson
S1-S3, S6 X1, X3		2-pole pin connector
S4		3-pole pin connector, or not equipped
IC1	TDA 5210	Infineon

Please note that in case of operation at 434 MHz a capacitor has to be soldered in place L2 and an inductor in place C6.

The following components are necessary in addition to the above mentioned ones for evaluation of the TDA5210 in conjunction with a Microchip HCS512 decoder.

Table 5-6 Bill of	of Materials Addendum	
Ref	Value	Specification
R7	100kΩ	0805, ± 5%
R8	10kΩ	0805, ± 5%
R9	100kΩ	0805, ± 5%
R10	22kΩ	0805, ± 5%
R11	100Ω	0805, ± 5%
R12	100Ω	0805, ± 5%
R13	100Ω	0805, ± 5%
R14	100Ω	0805, ± 5%
R21	22kΩ	0805, ± 5%
R22	10kΩ	0805, ± 5%
R23	22kΩ	0805, ± 5%
R24	820kΩ	0805, ± 5%
R25	560Ω	0805, ± 5%
C19	10pF	0805, COG, ± 5%
C21	100nF	1206, X7R, ± 10%
C22	100nF	1206, X7R, ± 10%
IC2	HCS512	Microchip
S5, X4-X9		2-pole pin connector
T1, T2	BC 847B	Infineon
D1	LS T670-JL	Infineon









#### **List of Figures**

# **List of Figures**

Figure 2-1	P-TSSOP-28-1 package outlines	2-3
Figure 3-1	IC Pin Configuration	3-2
Figure 3-2	Main Block Diagram	3-9
Figure 4-1	LNA Automatic Gain Control Circuitry	4-2
Figure 4-2	RSSI Level and Permissive AGC Threshold Levels	4-3
Figure 4-3	Data Filter Design	4-4
Figure 4-4	Determination of Series Capacitance Value for the Quartz Oscillator	4-5
Figure 4-5	Data Slicer Threshold Generation with External R-C Integrator	4-7
Figure 4-6	Data Slicer Threshold Generation Utilising the Peak Detector	4-7
Figure 4-7	ASK/FSK mode datapath	4-8
Figure 4-8	Frequency characterstic in case of FSK mode	4-9
Figure 4-9	Frequency charcteristic in case of ASK mode	4-10
Figure 4-10	Principle of the precharge circuit	4-11
Figure 4-11	Voltage appearing on C2 during precharging process	4-12
Figure 4-12	Voltage transient on capacitor C attached to pin 20	4-13
Figure 5-1	Schematic of the Evaluation Board	5-12
Figure 5-2	Top Side of the Evaluation Board	5-13
Figure 5-3	Bottom Side of the Evaluation Board	5-13
Figure 5-4	Component Placement on the Evaluation Board	5-14

List of Figures - 1



#### **List of Tables**

# **List of Tables**

Table 3-1	Pin Definition and Function	3-3
Table 3-2	FSEL Pin Operating States	3-10
Table 3-3	CSEL Pin Operating States	3-11
Table 3-4	MSEL Pin Operating States	3-12
Table 3-5	PDWN Pin Operating States	3-13
Table 4-1	Dependence of PLL Overall Division Ratio on FSEL and CSEL	4-6
Table 5-1	Absolute Maximum Ratings, Ambient temperature T <sub>AMB</sub> =-40°C + 105°C	5-2
Table 5-2	Operating Range, Ambient temperature T <sub>AMB</sub> = -40°C + 105°C	5-3
Table 5-3	AC/DC Characteristics with TA 25 °C, VVCC = 4.5 5.5 V	5-4
Table 5-4	AC/DC Characteristics with T <sub>AMB</sub> = -40°C + 105°C, VVCC = 4.5 5.5 V	5-9
Table 5-5	Bill of Materials	5-15
Table 5-6	Bill of Materials Addendum	5-16

## 单击下面可查看定价,库存,交付和生命周期等信息

>>Infineon(英飞凌)